

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Akira CHINDA et al.
Title: WIRING BOARD, SEMICONDUCTOR DEVICE, AND
PROCESS FOR PRODUCTION OF WIRING BOARD
Appl. No.: Unassigned
Filing Date: December 19, 2001
Examiner: Unassigned
Art Unit: Unassigned

PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Prior to examination of the present Application, Applicants respectfully request that the above-identified application be amended as follows:

IN THE CLAIMS:

In accordance with 37 CFR §1.121, please substitute for original claim 2, the following rewritten version of the same claim, as amended, and please renumber claims 40 - 43 (1st Claim 43) as claims 39-42 as shown below. The changes are shown explicitly in the attached "Versions With Markings to Show Changes Made."

2. (Amended) A wiring board as claimed in claim 1, wherein:
a thickness of said conductive member is $\frac{1}{2}$ or more of that of said insulating substrate.
39. (Amended) A process for the production of a wiring board as claimed in claim 37, wherein:
a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.
40. (Amended) A process for the production of a wiring board as claimed in claim 38, wherein:
a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.

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41. (Amended) A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with electroless plating method.

42. (Amended) A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with electroless plating method.

REMARKS

Applicants respectfully request that the foregoing amendments be made prior to examination of the present application.

Respectfully submitted,

Date: December 19, 2001

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Version with Markings to Show Changes Made

2. A wiring board as claimed in claim [2]1, wherein:

a thickness of said conductive member is $\frac{1}{2}$ or more of that of said insulating substrate.

[40.] 39. A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.

[41.] 40. A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.

[42.] 41. A process for the production of a wiring board as claimed in claim 37, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with electroless plating method.

[43.] 42. A process for the production of a wiring board as claimed in claim 38, wherein:

a step for forming said conductive member is effected by forming a nickel (Ni) plating in accordance with electroless plating method.